

AMENDMENTS TO THE DRAWINGS:

The attached sheet of drawings includes changes to Figure 7. This sheet, which includes Figures 6 and 7, replaces the original sheet including Figures 6 and 7.

In Figure 7, reference numeral "36S" is changed to reference numeral --36G--, to denote the gate lead.

Attachment: Replacement Sheet

REMARKS

The application has been amended to place the application in condition for allowance at the time of the next Official Action.

The title is amended to address the objection to the title noted in the Official Action.

A replacement drawing sheet is submitted for Figure 7, changing reference numeral 36S to reference numeral 36G to denote the gate lead consistent with the disclosure on page 14, lines 26, through page 15, line 3. The above-noted change to the drawings is the only change and is believed not to introduce new matter.

Claims 1-17 were previously pending in the application. New claims 23 and 24 are added. Therefore, claims 1-17, 23 and 24 are presented for consideration.

Claims 1-17 are rejected as anticipated by TAKAHASHI et al. (JP 2000-049184). This rejection is respectfully traversed.

Claim 1 provides that an inner portion of the lead element overhangs the semiconductor chip such that an inner end of the lead element is spaced apart from the top surface of the semiconductor chip.

Applicant notes that U.S. 6,307,272 is an English language equivalent of TAKAHASHI et al. and reference is made to the U.S. application because the drawing figures in the U.S. application are clearer than those in the Japanese application.

The position set forth in the Official Action is that inner end 20 of lead element 5 overhangs semiconductor chip 7. This position is believed untenable for the following reason:

The term "overhang" is defined as project over something that lies beneath. See for example the *American Heritage Dictionary of the English Language*, 4th ed. As seen in Figures 8-10 of TAKAHASHI, for example, inner portion 20 of lead 5 does not overhang the semiconductor chip 7. Rather, as seen in these figures, there is a gap (unnumbered) between the end of inner portion 20 and the semiconductor chip 7.

As the reference does not disclose that which is recited, the anticipation rejection is not viable. Reconsideration and withdrawal of the rejection are respectfully requested.

Claims 2-17 depend from claim 1 and further define the invention and are also believed patentable over TAKAHASHI et al.

In addition, the dependent claims include features not disclosed by TAKAHASHI. Claim 2 provides that a second lead element has an inner portion that overhangs the semiconductor chip such that an inner end of the second lead element is directly and electrically connected to a second electrode of the semiconductor chip using an electrically conductive paste.

As seen in Figure 10 of TAKAHASHI, for example, the second lead 6 neither overhangs the semiconductor chip 7 nor is directly connected to the semiconductor chip 7. Rather, as seen

in Figure 10, lead 6 is spaced apart from the semiconductor chip (both axially and laterally). Further, the bonding wire 14 connects lead 6 with electrode 12 such that lead 6 is not directly connected to electrode 12, using an electrically conductive paste.

Claim 6 also provides that a second lead element overhangs the semiconductor chip. The analysis above regarding claim 2 as to this feature is equally applicable to claim 6. Accordingly, at least claims 2 and 6 are believed patentable, regardless of the patentability of the claims from which they depend.

New claims 23 and 24 provide that an inner portion of a lead element overlaps the semiconductor chip. As set forth above with respect to claim 1, the leads of TAKAHASHI are spaced apart from the semiconductor chip and do not overlap the semiconductor chip. Support for the new claims is found in the drawing figures, original claim 1, and page 14, lines 26-31.

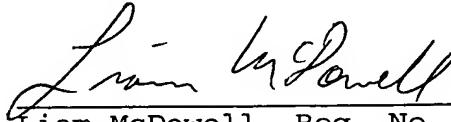
In view of the present amendment and the foregoing remarks, therefore, it is believed that the present application has been placed in condition for allowance. Reconsideration and allowance are respectfully requested.

The Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any

overpayment to Deposit Account No. 25-0120 for any additional
fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17.

Respectfully submitted,

YOUNG & THOMPSON



Liam McDowell, Reg. No. 44,231
745 South 23rd Street
Arlington, VA 22202
Telephone (703) 521-2297
Telefax (703) 685-0573
(703) 979-4709

LM/mjr
July 18, 2005

APPENDIX:

The Appendix includes the following item(s):

- a Replacement Sheet for Figure 7 of the drawings